

What is claimed is:

1. A method of supplying a substrate comprising the step of:

supplying a substrate on which a chip is to be mounted to a chip mounting apparatus in the form of a  
5 discrete substrate or an independent unit substrate consisting of a plurality of discrete substrates.

2. An apparatus for supplying a substrate on which a chip is to be mounted to a chip mounting apparatus, comprising:

a transport conveyor for transporting a  
5 substrate carrier for holding a discrete substrate or an independent unit substrate consisting of a plurality of discrete substrates, or a substrate for multiple devices consisting of a number of discrete substrates, and for feeding said substrate carrier or said substrate for  
10 multiple devices for a length corresponding to the size of said discrete substrate;

a stage having a disposition surface corresponding to the size of said discrete substrate; and

holding means for removably holding above said  
15 stage said unit substrate in said substrate carrier or said substrate for multiple devices transported by said transport conveyor to a position above said stage.

3. An apparatus for supplying a chip to a chip supply stage of a chip mounting apparatus, comprising:

a tray stage disposed near said chip supply stage for holding chip trays stacked in a plurality of layers, each of said chip trays holding a plurality of chips;

tray holding means for holding the second chip tray from the bottom of said chip trays stacked in layers to separate the lowermost chip tray from said held second chip tray; and

transport means for transporting said lowermost chip tray separated from said second chip tray from the bottom by said tray holding means to said chip supply stage.

4. A chip mounting system comprising:

the substrate supply apparatus according to claim 2;

the chip supply apparatus according to claim 3;

a chip mounting apparatus for mounting chips supplied by said chip supply apparatus on a substrate supplied by said substrate supply apparatus;

a box for surrounding an area in which said substrate and said chip are transported as a substantially closed space; and

a clean fan attached to said box for flowing clean air into said closed space.

5. The system according to claim 4, further comprising a substrate magazine for housing substrates formed to have openings at the front and back thereof and to have side plates covering its four faces, one of said openings of said substrate magazine being connected to said closed space to cause the other opening of said substrate magazine to serve as a discharge port of said closed space.